



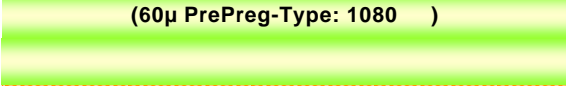









Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h + i
06	129	FR4	35	L20.35	P06_18_10	S1

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

06_129_FR4_35_L20.35_p06_18_10_s1

Layers	in μ	Material	Build-Up	Assembly			
Layer-1	35 μ	Copper		} A1			
	100 μ	Prepreg	(100 μ PrePreg-Type: 2125)				
	180 μ	Prepreg	(180 μ PrePreg-Type: 7628)				
Layer-2	35 μ	Copper			} A2		
	200 μ	L-FR4					
Layer-3	35 μ	Copper				} B	
	60 μ	Prepreg	(60 μ PrePreg-Type: 1080)				
	60 μ	Prepreg					
Layer-4	35 μ	Copper					} A1
	200 μ	L-FR4					
	35 μ	Copper					
Layer-5	180 μ	Prepreg		} A2			
	100 μ	Prepreg					
	55 μ	Copper					
Layer-99	55 μ	Copper			} B		

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